金属刀

Metal Bond Dicing Blades

产品概述：金属结合剂整体型切割砂轮采用同种材料制作，厚度薄、精度高，多用于高精度、小切深的切槽或切断。

Product overview: Metal bond dicing blades are made of identical material,with thin thickness and high precision, they are mainly used for grooving and cutting with high accuracy and narrow cutting depth.

主要特点：金属结合剂整体型切割砂轮对磨料把持能力强，精度高、耐磨性和形状保持性好、使用寿命长。

Main features: The grits are strongly held by the metal bond, high precision, minimized blade wear, good shape keeping ability and long life time.

主要应用领域：

半导体封装领域如 BGA、LGA、LED、二极管等半导体封装元器件的加工;

光学玻璃领域如滤光片、蓝玻璃、水晶及宝石等的加工;

光通讯领域如石英 V 槽加工及石英盖板的切断;

其它材料如磁性材料、硬质合金、工具钢、不锈钢等的切断或切槽。

Application

Semiconductor, such as BGA, LGA, LED, diode and so on.

Optical glass, such as filter, blue glass, crystal and gem.

Optical communication, such as slotting shape on quartz and cutting off quartz cover.

Other material, such as slotting and cutting off magnetic materials, carbide, tool steel and stainless steel.

供参考的典型规格及精度

Model specification and the precision for reference(mm)

D T	10~58	60~76.2	78~101.6	101.6~127	130~200	厚度公差 Thick tolerance
0.05						± 0.002
0.1						
0.2						
0.3						± 0.005
0.4						
0.5						
1.0						
1.5						
2.0						
H	6、8、9、10、12.7、25.4、31.75、40、41.275、50.8、76.2、69.875、88.9、114.3					

注：其他规格可根据用户图纸加工

Note：Other specifications can be produced according to customer's requirement